

**Amendments to Specification:**

**On Page 12, please replace the paragraph beginning on line 8 and ending on line 21 with the following amended paragraph:**

Examples of the above-introduced various embodiments are described in connection with FIGs. 5-8 (501, 601, 701, 801). Referring first to FIG. 5, this figure illustrates examples of processes 505 implemented by process recipes (which can be thought of as chamber level processes), and processes 503 implemented by sequence recipes (which can be thought of as tool level processes), that an exemplary tool may be qualified to perform. In the example of FIG. 5, check marks indicate qualifications (e.g., the binary form discussed above). In particular, in this example embodiment, the tool can be configured (and is qualified) to perform tool level Processes X, Y and Z (which may be processes to, e.g., deposit layers with different thickness and/or to clean wafers) as shown at 503. In addition, at the chamber level, FIG. 5 indicates that Chambers A and B are qualified to perform Processes A and B, while only Chamber C can be configured (and qualified) to perform Process C, as shown at 505. Again, the processes that Processes A, B and C represent can be any number of different types of processes, including processes for cleaning, etching and/or measuring.

**On Page 16, please replace the paragraph beginning on line 17 and ending on line 20 with the following amended paragraph:**

The above-listed quality of service parameters are provided as examples and do not represent an exhaustive list of possible quality of service parameters. Other similar parameters that can characterize the status of chambers and/or tools can also be used in conjunction with at least some ~~at least some~~ embodiments of the present invention.